



Material Content Data Sheet



Sales Product Name		IPD60R1K5CE		Issued		19. July 2018		
MA#		MA001581866						
Package		PG-TO252-3-343		Weight*		311.49 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.513	0.49	0.49	4858	4858
leadframe	non noble metal	iron	7439-89-6	0.137	0.04		441	
	inorganic material	phosphorus	7723-14-0	0.041	0.01		132	
	non noble metal	copper	7440-50-8	137.105	44.03	44.08	440154	440727
wire	non noble metal	aluminium	7429-90-5	4.363	1.40	1.40	14008	14008
encapsulation	organic material	carbon black	1333-86-4	1.297	0.42		4165	
	plastics	epoxy resin	-	24.651	7.91		79140	
	inorganic material	silicondioxide	60676-86-0	103.795	33.32	41.65	333219	416524
leadfinish	non noble metal	tin	7440-31-5	3.834	1.23	1.23	12307	12307
solder	noble metal	silver	7440-22-4	0.043	0.01		138	
	non noble metal	tin	7440-31-5	0.034	0.01		110	
	non noble metal	lead	7439-92-1	1.640	0.53	0.55	5266	5514
heatspreader	non noble metal	iron	7439-89-6	0.033	0.01		106	
	inorganic material	phosphorus	7723-14-0	0.010	0.00		32	
	non noble metal	copper	7440-50-8	32.995	10.59	10.60	105924	106062
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com